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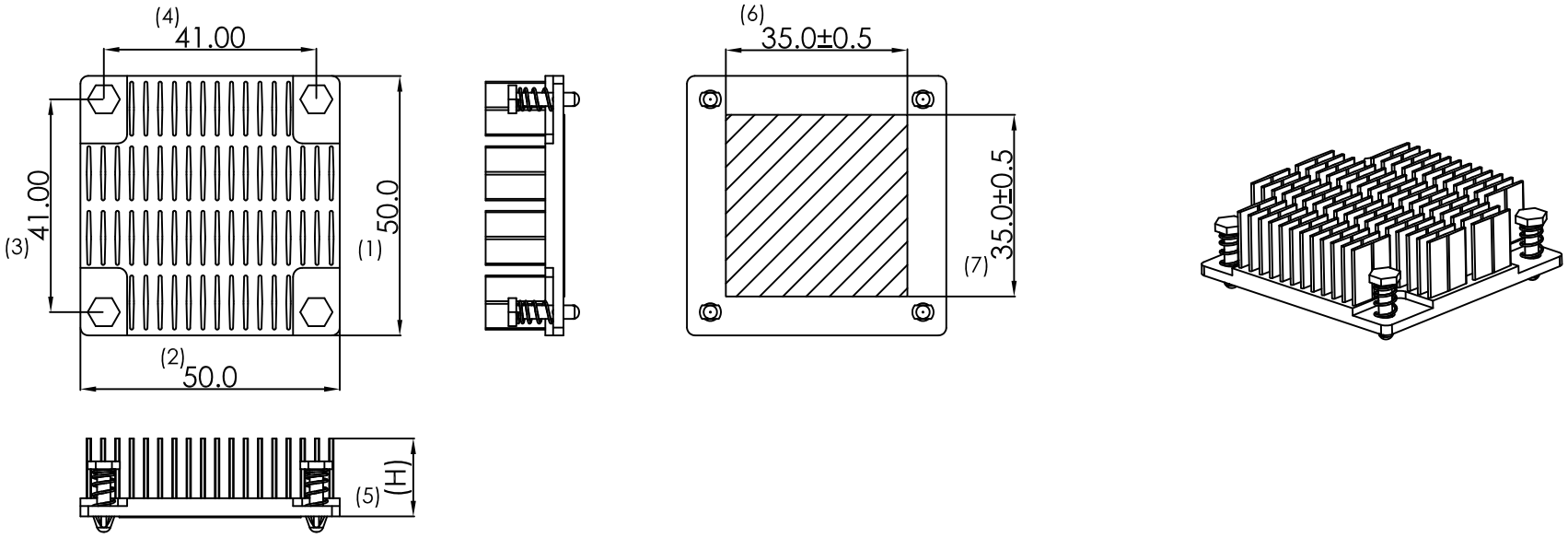
APPROVAL SHEET

BRAND	REGO
PART NUMBER	FP4H50004-xx35BA-100T-A+PCM
DESCRIPTION	HEAT SINK ASSEMBLY 50 x 50 x (8~40)mm
CUSTOMER	
CUSTOMER P/N	

AUTHORIZED SIGNATURES			
NAME			
DATE			



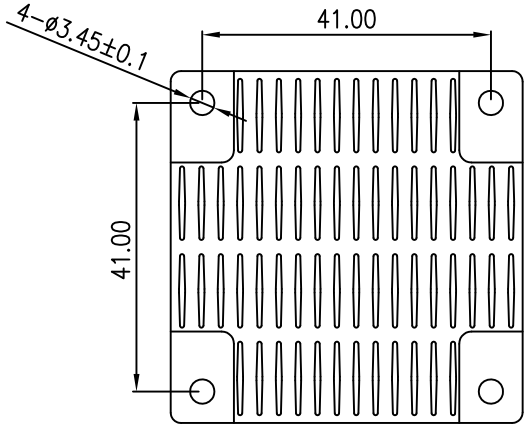
NOTES:

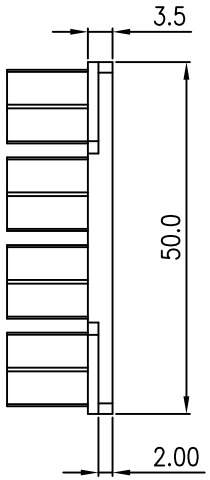
PART NAME / NUMBER	HEIGHT(H)	FORGED FIN	PCS	PUSH PINS	PCS	PHASE CHANGE THERMAL PAD	PCS
FP4H50004-0835BA-100T-A+PCM	8	FP4H50004-0835BA-1	1	1-1700010925	4	PCM4988 35x35x0.2	1
FP4H50004-1035BA-100T-A+PCM	10	FP4H50004-1035BA-1					
FP4H50004-1535BA-100T-A+PCM	15	FP4H50004-1535BA-1					
FP4H50004-2035BA-100T-A+PCM	20	FP4H50004-2035BA-1					
FP4H50004-2535BA-100T-A+PCM	25	FP4H50004-2535BA-1					
FP4H50004-3035BA-100T-A+PCM	30	FP4H50004-3035BA-1					
FP4H50004-3535BA-100T-A+PCM	35	FP4H50004-3535BA-1					
FP4H50004-4035BA-100T-A+PCM	40	FP4H50004-4035BA-1					

COMPRESSION REFERENCE

CONDITIONED	H+T = 2.9mm IC HEIGHT (H) PCB THICKNESS (T)	H+T = 3.4mm IC HEIGHT (H) PCB THICKNESS (T)	H+T = 3.9mm IC HEIGHT (H) PCB THICKNESS (T)	H+T ≧ 4.4mm IC HEIGHT (H) PCB THICKNESS (T)
APPLIED FORCE (3~5 lbs)	3.65 lbs	4.07 lbs	4.5 lbs	TO BE AVAILABLE AT ADDITIONAL CUSTOMIZATION

PROJECT	APPROVED: CHRIS	MATERIAL: N/A	DATE: 2023/05/12	.X° ± 3°
TITLE: HEAT SINK ASSEMBLY 50 x 50 x (8~40)mm	CHECKED: LEVI	FINISH: N/A	SCALE: 1 : 1	.X ± 0.30 / .XX ± 0.20 / .XXX ± 0.10
PART NO: FP4H50004-xx35BA-100T-A+PCM	DRAWN: VIC	UNITS: mm	REV: A	SHEET: 1 OF 1

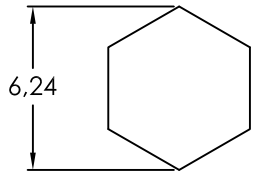


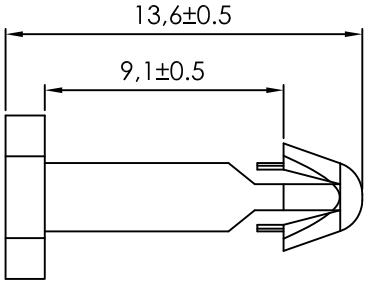


NOTES:

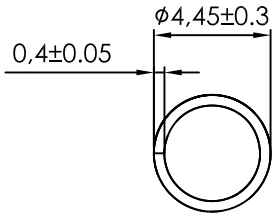
PART NAME / NUMBER	HEIGHT(H)
FP4H50004-0635BA-1	6
FP4H50004-0835BA-1	8
FP4H50004-1035BA-1	10
FP4H50004-1535BA-1	15
FP4H50004-2035BA-1	20
FP4H50004-2535BA-1	25
FP4H50004-3035BA-1	30
FP4H50004-3535BA-1	35
FP4H50004-4035BA-1	40

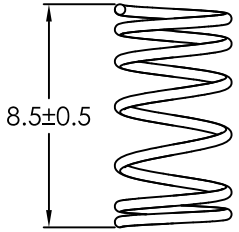
PROJECT	APPROVED: CHRIS	MATERIAL: AL1070	DATE: 2023/05/12	.X° ± 3° / .X ± 0.30 / .XX ± 0.20 / .XXX ± 0.10
TITLE: FORGED FIN 50 x 50 x (6~40)mm	CHECKED: LEVI	FINISH: BLACK MATTE ANODIZED	SCALE: 1 : 1	
PART NO: FP4H50004-xx35BA-1	DRAWN: VIC	UNITS: mm	REV: A	SHEET: 1 OF 1

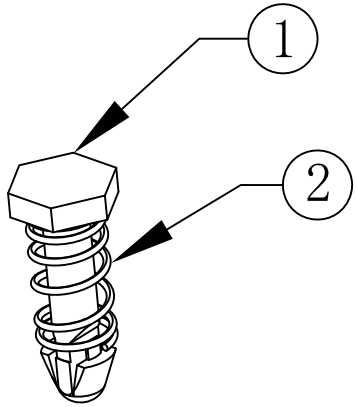




HOLE IN PCB ø3.1±0.05







ITEM	DESCRIPTION	MATERIAL	FINISH
1	BODY	NYLON 66	BLACK
2	SPRING	PIANO WIRE	NICKEL

ITEM		NUMERICAL VALUE
SPRING DIAMETER	D=	4.05 mm
WIRE DIAMETER	d=	0.4 mm
TOTAL COIL Q'TY	Na=	6
FREE LENGTH	L0=	8.5 mm
SPRING COEFFICIENT	K=	96.34 g/mm

REGO

PROJECT	APPROVED: CHRIS	MATERIAL: SEE NOTE	DATE: 2020/10/20	.X° ± 3° / .X ± 0.30 / .XX ± 0.20 / .XXX ± 0.10
TITLE: PUSH PIN	CHECKED: LEVI	FINISH: SEE NOTE	SCALE: 1 : 1	
PART NO: 1-1700010925	DRAWN: VIC	UNITS: mm	REV: A	SHEET: 1 OF 1

PCM4988

High Thermal Conductivity Phase Change Material

Honeywell's PCM4988, a highly thermally conductive Phase Change Material (PCM) in pad format, was designed to minimize thermal resistance at interfaces. Based on a novel polymer PCM system, this material exhibits excellent wetting at interfaces during typical operating temperature range, resulting in very low surface contact resistance.

A proprietary filler material provides high thermal conductivity (2.0–5.0 W/m°C) and a low thermal impedance (<0.20°C cm^2/W), suitable for high performance IC devices.

PCM4988 in Convenient Pad Format

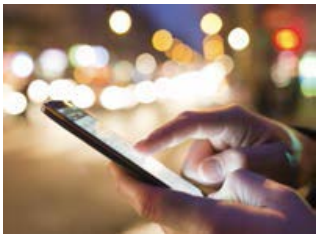
*Stencil printable material is available as PCM4988-SP

Honeywell TIMs Serve Multiple Applications

Automotive & Power

IT/Enterprise

Telecommunications



Consumer Electronics

FEATURES & BENEFITS

- High performance filler and polymer technology
- Phase change at 45°C
- Highly conductive filler loading to optimize performance
- Superior handling and reworkability
- Superior reliable thermal performance
- Excellent thermal capability to fit different needs

PCM4988 Technical Information

Physical Properties	Unit	Test Method	PCM4988
Thermal Conductivity	W/m·K	ASTM D5470	2.0
Thermal Impedance @ no shim (Typical Value)	°C -cm^2/W	ASTM D5470 Modified	0.14
Specific Gravity		ASTM D374	2.2
Viscosity (Typical Value)	Pa·s @2 1/s, 25°C	RehometerHON	NA
Volume Resistivity	Ω·cm	ASTM D257-700	8.2x10^{14}
Thickness Range	mm		0.20-1.00

STORAGE CONDITION

Refer to product label.

THERMAL IMPEDANCE POST RELIABILITY

(No shim @ 40psi)

End of Line 0.14 °C-cm^2/W

Temperature Cycle "B" 0.10 °C-cm^2/W

(-55°C to +125°C , 1000 cycles)

Product Use

Clamping pressure and temperature are suggested to achieve a minimum bond line thickness of the thermal interface material, typically less than 1.5 mil (0.038mm) for best thermal performance.

More Honeywell TIMs

PCM4988 is part of Honeywell's TIM Solutions family of phase change materials. Whatever the thermal challenge, we offer a TIM product that provides just the right characteristics for your application. Find out more about:

PTM7000 Series
PTM6000 Series
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PCM45F Series
Hybrid Series
LTM Series By

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